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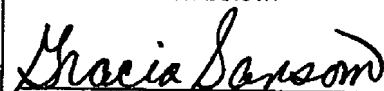
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: TREJO, LUIS
Patent/Application No: 6,898,849
Granted/Filed: 05/31/2005
Art Unit:
Examiner:
Docket No.: TI-21129
Conf. No.: 4601
Customer No.: 23494

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NAME OF INVENTOR(S): TREJO, LUIS		RECEIPT DATE & SERIAL NO.: Patent/Appln No.: 6,898,849	
TITLE OF INVENTION: METHOD FOR CONTROLLING WIRE BALLS IN ELECTRONIC BONDING		Grant/Filing Date: 05/31/2005	
TI FILE NO.: TI-21129	DEPOSIT ACCT. NO.: 20-0668		
FAXED: 02/21/2008			
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